

# GENE-APL6

## Thermal Image Analysis Report

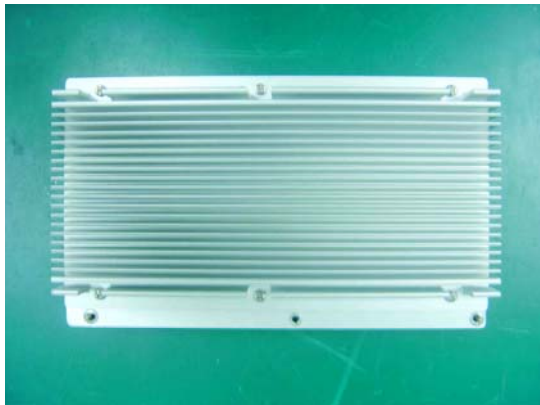
Summary	<input type="checkbox"/> <b>Pass</b>  <input type="checkbox"/> <b>Fail</b>  <input checked="" type="checkbox"/> <b>Pass with Deviation</b> <b>Comment:</b> <u>There are 6 temperature points marginal passed, the functions are stable.</u>				
	<b>Test Result Summary</b>				
	Critical	Major	Minor	Enhancement	
Defect Found	0	0	0	6	
Defect Unsolved	0	0	0	6	

Issue date	QE Manager	Test Engineer
2017 / 11 / 21	KJ Wang	Juno Cheng

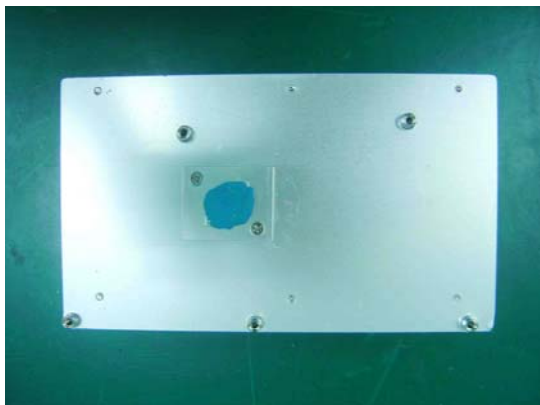
## Sample Configuration & Quantity Under Test

- **Model name : GENE-APL6 A0.2**
- **CPU : Intel Apollo Lake N4200 / 1.1GHz**
- **Memory : Transcend 8GB\*1 / DDR3L 1866 / Micron 6EN77 D9RVX**
- **HDD : TOSHIBA MK1676GSX / 160 GB**
- **BIOS : GENE-APL6 R0.3 (GAP6AM03) (09/05/2017)**
- **Test Software : Windows 10 / Run PassMark Burn In Test 8.1 Pro**
- **Power : HG2-6400P**
- **CPU Heat Sink :**

Heat Sink



Heat-Spreader + Thermal Pad



# Thermal Image Analysis

**1. Test Date: 2017-11-21**

**2. Test Product: GENE-APL6**

**3. Test Site: AAEON QE Dept.**

**4. Temperature Measurement:**

**4.1. 10 Channel Thermal Recorder:**

**4.1.1 OMRON**

**4.1.2 Model: ZR-RX25**

**Date of Calibration: 2016/11/30**

**Serial Number: TH-149**

**4.2. IR Scanner: Infrared Camera**

**4.2.1 NEC Avio Infrared Technologies Co., Ltd.**

**4.2.2 Model: Thermo GEAR G100W2-D**

**Date of Calibration: 2016/11/29**

**Serial Number: 1051444**

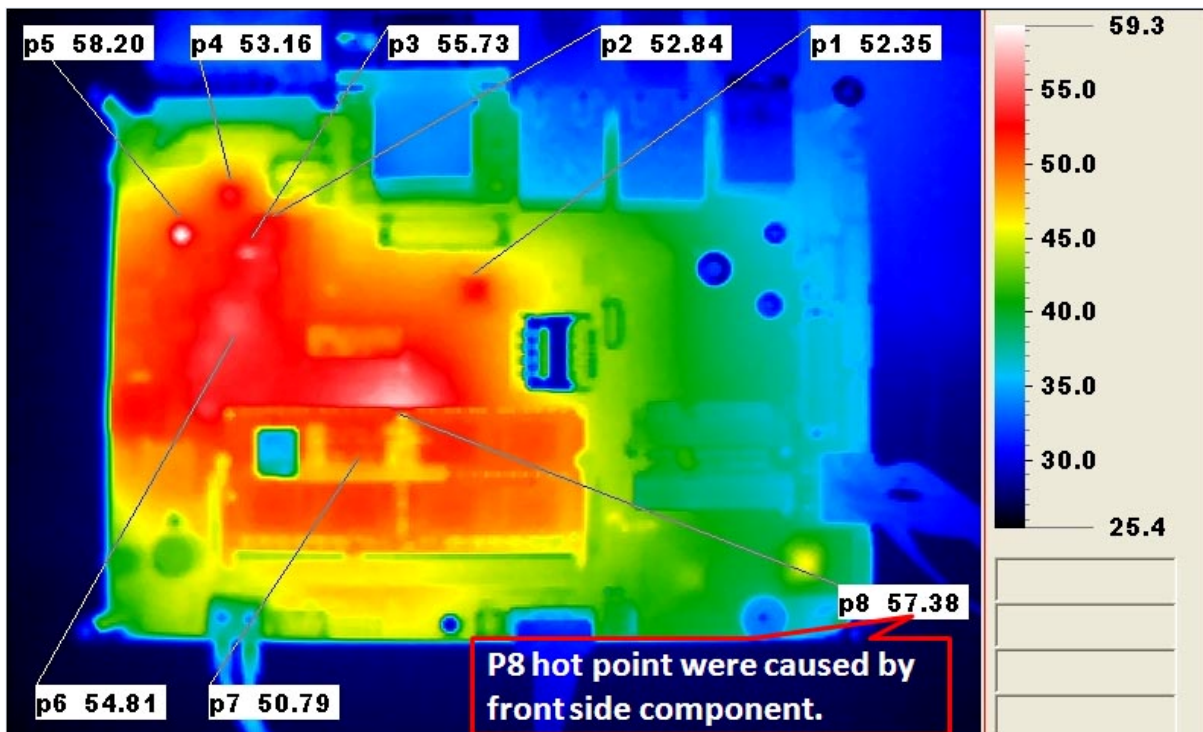
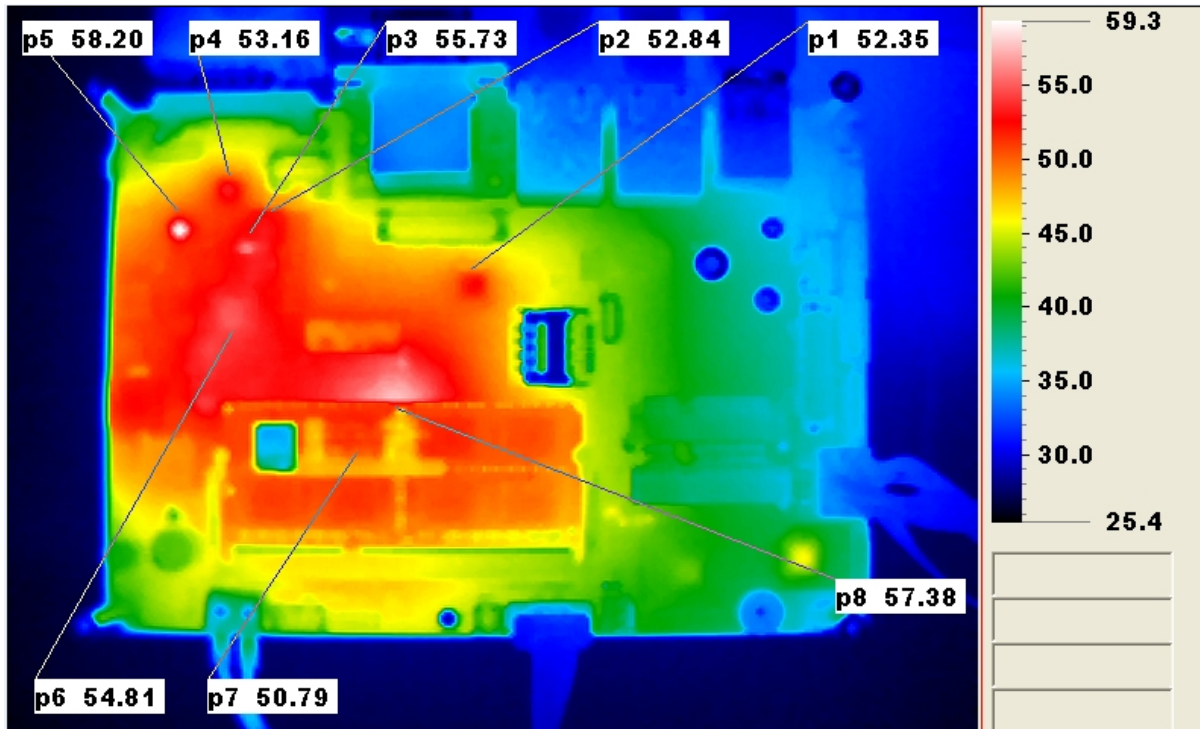
**5. Test Condition:**

**Test by DA-100: 25.0°C with Heat Sink**

**6. Take Picture Time:**

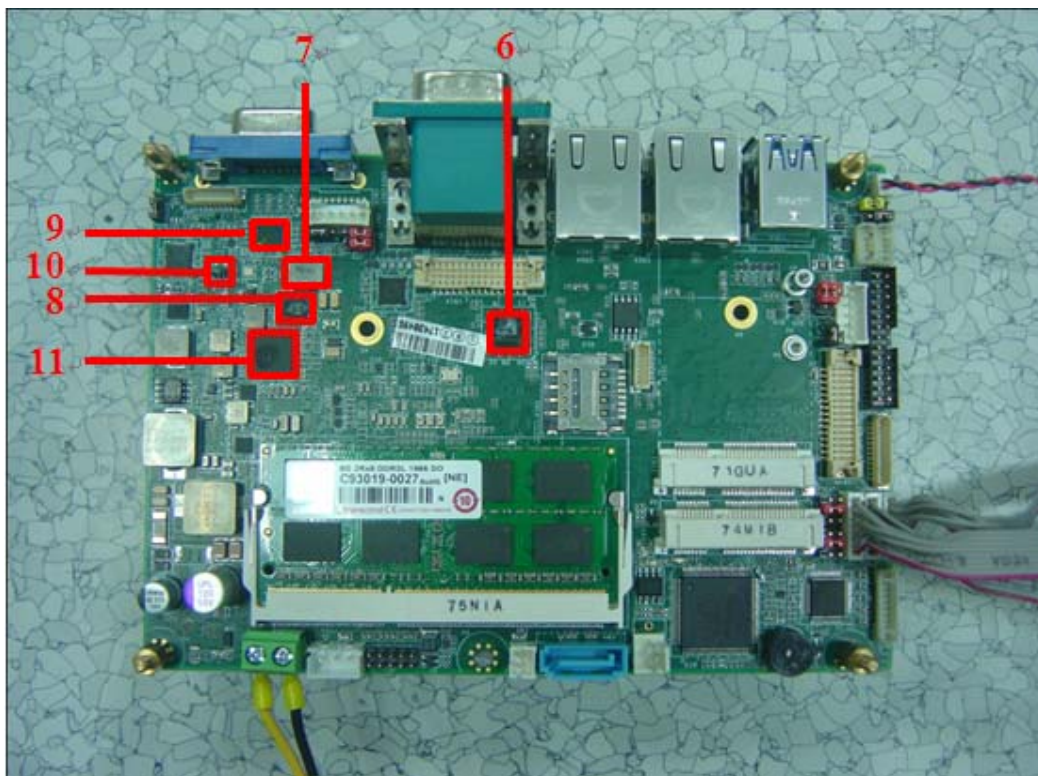
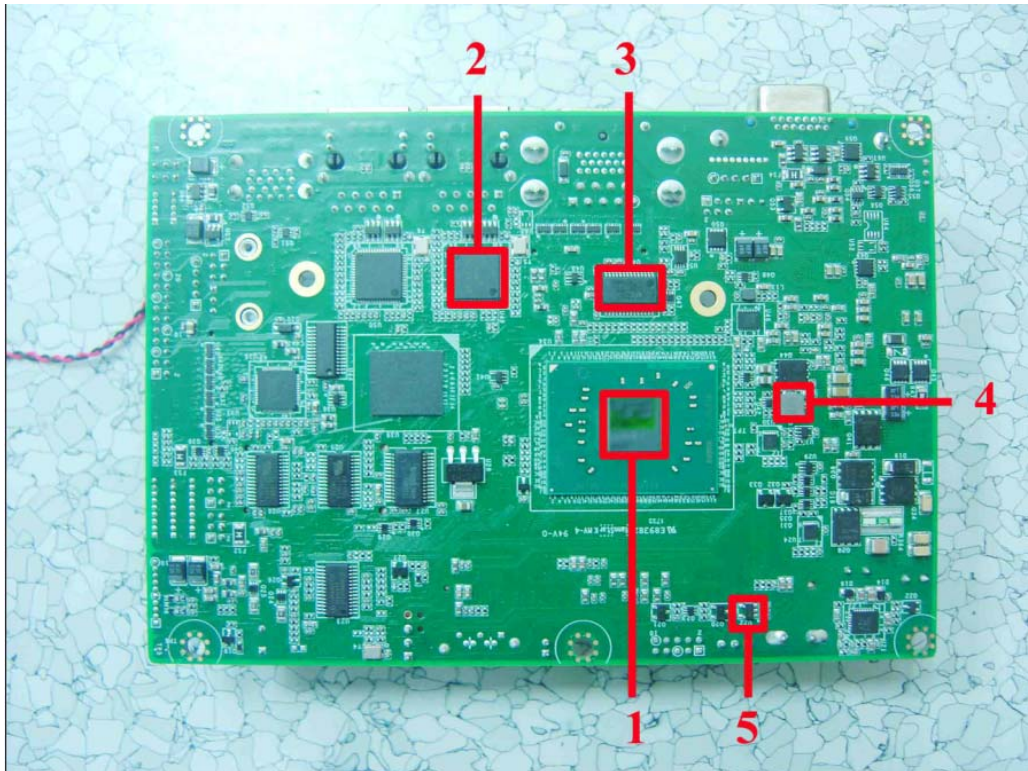
**After power on 2 hours**

**Temperature Profile Test:**  
**Component Side:**



### Terminal Recorder:

Measuring Thermal Couple Position :



Using OMRON / ZR-RX25 test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)		TPT(*3)	Note
				26.0°C	60°C		
1	U34	(TF)INTEL CPU.Apollo Lake.Pentium N4200.2.5GHz	105	53.8	88.8		
2	U49	(TF)IC.PCI-E GigaBit Ethernet Chipset. Intel.I211AT	85	54.1	89.1	Note 4	
3	U47	(TF)IC.RS232 Driver/Receiver. TI.TRS213IDBR	85	53.6	88.6	Note 4	
4	L12	(TF)Coil.0.47uH.DCR=14mΩ.Idc=7.5A. HDT.MPCA-0420-R47-	125	59.6	94.6		
5	U22	(TF)IC.Regulator.EXAR.SPX5205M5-L-5.0	125	57.8	92.8		
6	U9	(TF)IC.Display Port to LVDS Converter NXP.PTN3460IBS/F2MP	96.8	56.0	91.0	Note 4	
7	L8	(TF)COIL.CYNTEC.PCMB063T-R22MS	125	56.8	91.8		
8	Q15	(TF)PWR.DUAL N-MOSFET.FAIRCHILD.FDMS3664S	100	56.7	91.7	Note 4	
9	U19	(TF)IC.DisplayPort to VGA Converter. Chrontel.CH7517A-BF	125	57.5	92.5		
10	U13	(TF)IC.LDO. ANPEC.APL5325BI-TRG	100	65.8	100.8		
11	U7	(TF)IC.PMIC.Intel Apollo Lake TI.TPS650942A0RSKR	100	59.7	94.7	Note 4	
12		Memory chipset	95	57.2	92.2	Note 4	

Note(\*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
  - "TAT" indicates the actual measured temperature under product specification.
  - "TPT" indicates the predicted temperature under 25°C working environmental.
  - Judgment Criteria:**
    - **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
    - **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.
- For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.
- RTC battery avoid to put on heat position.** Please do not exceed battery temperature specification.
  - Defect NO.** : [000000LABD01](#)